

Model **KISS-103**
"Keep It Simple Soldering"
18" x 24" PCB Platform



Made in America

FEATURES:

The **KISS-103** is a fully configured Selective Soldering Machine ready to produce your product. The **KISS-103** includes the following standard features:

- "Super Quick" motion for fastest processing times.
- Safety cover with internal lighting and fume vents.
- Universal PCB location rails with motor driven adjustment.
- Solder pot and pump assembly.
- 6mm and 12mm "Bullet" nozzles.
- Heated Nitrogen to the solder nozzle.
- Windows XP O/S with simple on or off line programming.
- Rapid setup and time to "first production" using CAD importing or on the machine "teach" functions.
- Programmable flux deposition.
- Programmable solder wave flow rate.
- Automated in process solder wave height check / adjust.
- Automated solder pot level check and fill.
- Fiducial alignment prior to starting a process.
- Set the time/temp profile for each individual component type for maximized process control and TAKT time.
- Absolute control over all critical process parameters:
 - Solder temperature interlocked to within 2 degrees C.
 - Height, and travel speed of the solder wave.
 - Programmable initial pre-heat soak time
- Will Process PCBs 18" x 24" unassisted (flux and solder) and up to 18" x 42" with manual step over.
- Step and repeat capability in both X and Y axis for multiple boards in a panel.
- Set-up kit, on site installation and training included.
- One year guarantee covering the entire machine and two years for the solder pot and pump assembly.

ADVANTAGES:

The **KISS-103** is an automated, simple to use low cost selective soldering machine using the proven "traveling mini-solder wave". It is used to flux and solder through hole components on SMT boards within close proximity of adjacent components. This process overcomes the limitations of operator dependent soldering with a truly flexible automated flux application and molten solder delivery system.

The **KISS-103** couples high throughput with precise process controls. The programmable features provide the tools to set all process parameters, including immersion depths, pre-heat dwells, travel distances and speeds, solder temperature and wave height. Once set, the system will repeat precisely.

The **KISS-103** will out produce 5 or more operators soldering with an iron while significantly increasing the solder joint quality and to a predictable schedule.

"You can expect a ROI of 6 months or less"

PROCESS OVERVIEW:

The operator places the PCB onto the location rails and starts the automated cycle. The cycle begins by applying flux to all the programmed sites. Next the mini solder wave is automatically moved under the component to be soldered. The solder nozzle raises to "wet" the first pins. The solder wave travels the length of the component soldering the through hole leads to the PCB. At the completion of the travel the solder pot lowers and moves to the next site. All programmed sites are soldered in the same cycle. An automated stepping function allows solder arrays of boards in an X-Y matrix. After completing the cycle the pot returns to the start position ready for the next cycle.

APPLICATIONS:

The **KISS-103** is designed to selectively solder components such as connectors and leaded through hole components into printed circuit boards, panels, and other assemblies without disturbing nearby SMT components.



SOLDER POT: (for lead and lead-free alloys)

The lead-alloy solder pot wetted surfaces are constructed of specially treated 316 stainless steel. The optional Lead-Free alloy solder pots are constructed of Titanium to withstand attack from aggressive tin rich alloys. The heaters are sized to bring the solder safely to temperature within an hour. Recirculation of solder is accomplished via a programmable motor coupled to a precision impeller assembly that delivers the precise and consistent volume of solder to the nozzle. The solder distribution system is designed to minimize dross build up while providing an extremely consistent and repeatable solder wave shape.

A heated nitrogen blanket captured within the enclosed solder pot inerts the molten solder surfaces minimizing dross. The heated nitrogen surrounds the solder nozzle and solder site as the solder wave contacts the terminals minimizing icicles and solder bridges while providing an inerted return of the solder back into the pot.

The solder temperature is interlocked within $\pm 2^{\circ}\text{C}$ of set point. The capacity of the solder pot ensures sufficient solder mass for even the largest assemblies.

The nozzles are magnetically fixed and can be exchanged in seconds. A full set of "Bullet Nozzles" are supplied with the system. These are sufficient for most applications. Additional "Wave Nozzles" and special purpose nozzles are available enabling selective soldering of wide patterns (multiple rows) in close proximity to previously soldered components without danger of reflowing them (see the KISS nozzle data sheet).

PROGRAMMING:

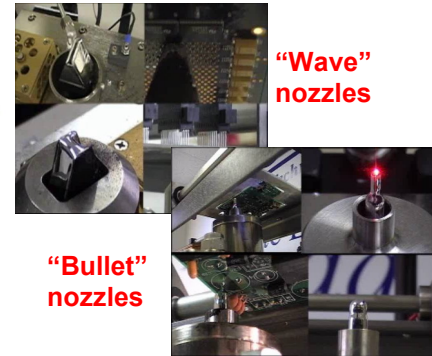
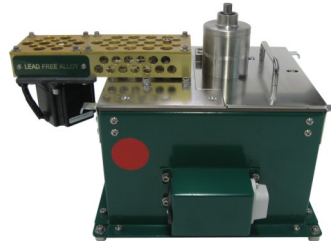
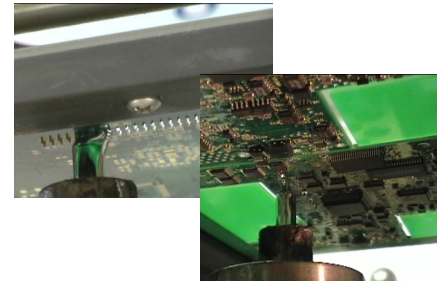
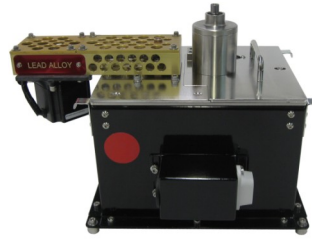
The initial programming is accomplished by one of two methods. At a desktop or on the machine..... At your desktop import the PCB CAD file into the KISSware program. Pick the solder nozzle size (this becomes your cursor). Choose the start/stop positions for all devices to be soldered. The process path becomes highlighted and script is automatically created for you. Circular or angular interpolation allows the soldering of large round arrays in a spiral pattern and connectors not perpendicular to the X-Y plane.

Optionally, use the set up camera viewed on the monitor and joystick function on the keyboard to set the flux and solder pattern in real time. Usually an average board can be programmed within 15 minutes. You can fine tune the X,Y and Z positions, speeds, solder wave height and other parameters to perfect the process. Start the cycle.

OPTIONS: (see individual data sheets)

- Titanium solder pot for lead-free alloys
- Additional solder nozzles
- In process top side pre-heat with pyrometer controls
- Drop jet spray head
- De-bridging Nitrogen Jet
- Closed loop position feedback with linear encoders
- Solder pot exchange cart with pot warmer controller

"The soldering process"



SPECIFICATIONS:

PCB Panel Size

| Minimum | Maximum |
|-----------------------------------|-----------|
| 2" x 2" | 18" x 24" |
| (18" x 42" with manual step over) | |

Safe "Keep Away"

(distance to adjacent pads) 1mm

Motion (Super Quick)

- Z-Axis Accuracy/Repeatability +/- .002" Speed 0-4 inches/sec.
- X and Y Axis Accuracy/Repeatability +/- .002" Speed 0-6" inches/sec.

Solder Pot

- Temperature PID proportioning (0-400°C) $\pm 2^{\circ}\text{C}$
- Solder Capacity 30 lbs.
- Pump PC controlled

Controls

PC with Windows XP O.S.

Physical

- Dimensions 55" wide x 62" deep x 54" high
- Weight 625 lbs.

Facilities

- Power 120VAC/1 Ph/60 Hz 15 amps
- Air 80 - 90 PSI
- Nitrogen 15 - 50 CFH @ 60 - 70 PSI
- Exhaust 350 CFM recommended (2) 4" dia. Take-offs at rear panel

CERTIFICATION of COMPLIANCE:

OSHA, NEC, CE, UL, ULC

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Call for a free video of the KISS machines: and the selective soldering process:

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